09-27	7-1999 EXPRESS MAIL: E1266889596US
FGRM PTO-1595 RECO	U.S. DEPARTMENT OF COMMERCE
	55718
Name of Party(ies) conveying party(ies)	Names and address of party(ies) receiving an interest:
TRI-RUNG YEW; WATER LUR; AND HSIEN-TA CHUNG	Name: UNITED MICROELECTRONICS CORP. Internal Address:
Additional Name(s) of conveying party(ies) attached? [] Yes [X	Street Address: NO. 3, LI-HSIN RD., II, SCIENCE-BASSINDUSTRIAL PARK
	City: HSINCHU State: Zip: Zip:
Nature of conveyance: [X] Assignment [] Merger	Additional name(s) & address(es) attached? [] Yes [X] No
[] Security Agreement [] Change of Na [] Other	99/345906
Execution Date:	
4. Application number(s) or patent number(s): N / A If this document is being filed together with a new application, the execution date of the application is: Aug. 17, 1999 A. Patent Application No.(s) B. Patent No.(s)	
72/22/1999 ASELIMM 6000001 93393905 Additional numbers attached? [] Yes [] No	
concerning document should be mailed:	Total Number of applications and registrations involved: [1]
Name: CHARLES C.H. WU Internal Address:	7. Total fee (37 CFR 2.6(b)(6))
Street Address: _2030 MAIN STREET	8. Deposit account number:
City: IRVINE State: CA Zip: 92614-7254	(Attach duplicate copy of this page if paying by deposit account)
9. Statement and signature. To the best of my knowledge and belief, the forgoing information is true and correct and any attached copy is a true copy of the original document.	
CHARLES C.H WU Name of Person Signing Signature Total number of pages including cover sheet, attachments, and document: [4] Mail documents to be recorded with required cover sheet information to: Commissioner of Patents and Trademarks, Box Assignments	

CONTINUATION OF PART 2

NAME: UNITED SILICON INCORPORATED

STREET ADDRESS: NO. 3, LI-HSIN ROAD, SCIENCE-BASED INDUSTRIAL PARK

HSINCHU, TAIWAN, R.O.C.

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PATENT REEL: 010259 FRAME: 0476

EXPRESS MAIL: EI266889596US

ASSIGNMENT

WHEREAS,

1. Tri-Rung Yew

- 2. Water Lur
- 3. Hsien-Ta Chung

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: METHOD FOR MANUFACTURING DIELECTRIC LAYER

[] Filed: Serial No.

[x] Executed concurrently with the execution of this instrument

WHEREAS, 1. United Microelectronics Corp., of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

2. United Silicon Incorporated, of No. 3, Li-Hsin Rd. II, Science-Based Industrial Park, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

-1-

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s)

Signature:

Sole or First Joint Inventor: Tri-Rung Yew

Signature:

Second Joint Inventor (if any): Water Lur

Third Joint Inventor (if any): Hsien-Ta Chung

RECORDED: 09/11/1999